Substrate Compatibility Test Report

Date: 3/30/10
Material: BOPP Label
Machine: WS6000 / Nr.
Location: RIT
Certification Number: RI6000-10-1749

SUBSTRATE TEST DETAILS

Supplier name: Avery Dennison - FRNA
Media name: 2.3 mil White BOPP IT/C/SG9N/1.2 mil PET

<table>
<thead>
<tr>
<th>Category</th>
<th>Self-adhesive</th>
<th>Flexible Packaging</th>
<th>Paper</th>
<th>Shrink Sleeve</th>
<th>Synthetic</th>
<th>Magnetic</th>
<th>Cartonboard</th>
<th>IML</th>
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</thead>
<tbody>
<tr>
<td>Region:</td>
<td>Europe</td>
<td>× US LA</td>
<td>×</td>
<td>Canada</td>
<td>×</td>
<td>APJ</td>
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<tr>
<td>Media type:</td>
<td>Paper</td>
<td>PE</td>
<td>PC</td>
<td>PET</td>
<td>×</td>
<td>× PP/BOPP</td>
<td>PLA</td>
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<td></td>
<td>PVC</td>
<td>PC</td>
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<td>OPS</td>
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<td>Specialty</td>
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</table>

Test description: Official substrate compatibility test for industrial presses ws6000.

Test procedure: Screen test   × Full test

Shipping condition received goods: firmly wrapped and protected to stabilize environmental conditions

Setup (default): Ink version: 4.5
Blanket code: NSJ4510020000
 Pip code: UL201247
ITM default temperature: 105 degr. C.

Substrate behaviour: Bleeding: None
Telescopic: None
Static: None
Jams: None

Necessary print cleaners: 1

Ink adhesion: Pass
after 15 mins. = 100%
after 60 mins. =

 Forced colour test: Cyan: Pass
Magenta: Pass
Yellow: Pass
Black: Pass

Temperature mapping: 95 degr. = 100%
105 degr. = 100%
115 degr. = 100%

Press settings (best working point) PTH 55
Blanket = 105
Feed fan = 6
2nd Transfer = 200

Test result/conclusion:  × PASS   FAIL

Additional remarks/comments: